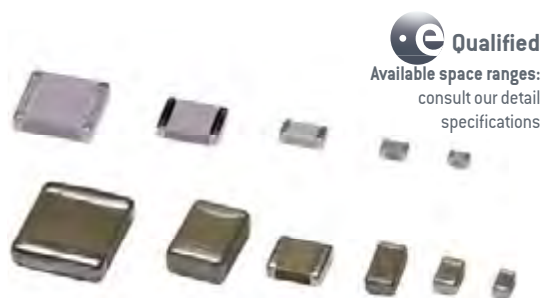


CEC / CNC Series

Low and Medium Voltage Chips Capacitors



CEC Qualified
Available space ranges:
consult our detail
specifications

In accordance with the specifications of CECC 32101 and NF C 93133 standards

FEATURES

- Case sizes: 0402 - 3040
- NP0, BX, 2C1, X7R dielectrics
- Capacitance range: 1pF to 12μF
- Ag/Pd/Pt, Ni barrier, epoxy terminations available
- RoHS and Non RoHS compliant capacitors available
- Screening in accordance with ESA specifications available

PHYSICAL CHARACTERISTICS

CONSTRUCTION

MLCC capacitors for surface mounting with optional Nickel barrier

MARKING (on request)

Capacitance value coded (from 0805 to 3040 sizes).

PACKAGING (see page 13)

S8* = available for 0402 to 1210 sizes.

S12* = available for 1812 to 2220 sizes.

BA* = available for 0402 to 2220 (except 0907) sizes.

* not available with H, HW and E, terminations

HOW TO ORDER

CNC4	-	C	M	F	56nF	10%	50V	S8	T5
Series	Bismuth	Termination	Marking	Quality level	Capacitance	Tolerance	Rated voltage	Packaging	Reliability level
CEC •• NP0 Ceramic	Option A (= bismuth free dielectric) available on request. Please consult us.	W = RoHS compliant		- = no marking	Capacitance value in clear	NP0: cap. value ≤ 12pF ±0.25pF cap. value ≤ 8.2pF ±0.5pF ±1pF cap. value > 22pF ±1% cap. value > 12pF ±2% cap. value > 8.2pF ±5% ±10% cap. value > 3.9pF ±20%	10V 16V 25V 50V 100V 200V 500V 1000V Intermediary and higher voltages available on request.	- = Exxelia packaging S8* = available for 0402 to 1210 sizes. S12* = available for 1812 to 2220 sizes. BA* = available for 0402 to 2220 [except 0907] sizes. * not available with H, HW and E, terminations see page 13	For F parts only. Acc. to Exxelia spec. - T5 T6 See page 15
		- Ag/Pd/Pt Q Ag* H Ag/Pd/Pt + dipped Sn/Pb 60/40 C Ag + Ni** + electrolytic Sn/Pb 95/5 D Ag + Ni*** + electrolytic Sn/Pb 60/40 E Ag + Ni**** + dipped Sn/Pb 60/40 G Ag + Ni + Au YC Ag + Polymer + Ni + Sn/Pb 95/5 YD Ag + Polymer + Ni + Sn/Pb 60/40 YG Ag + Polymer + Ni + Au	W Ag/Pd/Pt QW Ag HW Ag/Pd/Pt + dipped Sn CW Ag + Ni + electrolytic Sn - GW Ag + Ni + Au YCW Ag + Polymer + Ni + Sn - YGW Ag + Polymer + Ni + Au	M = Marking: capacitance value coded (from 0805 to 3040 sizes).					
CNC •• BX, 2C1, 2R1/X7R Ceramics	See Ratings and Case code table					BX, 2C1 and X7R: ±5% ±10% ±20%			

ELECTRICAL SPECIFICATIONS

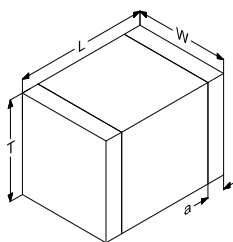
Description	NP0
Operating temperature	-55°C to +125°C
Climatic category	55 / 125 / 56
Rated voltage (U _{RC})	10V _{DC} to 1,000V _{DC}
Maximum ΔC/°C over temperature range without DC voltage applied	NA
Maximum ΔC/°C over temperature range with rated voltage applied	NA
Temperature coefficient with or without DC voltage applied	[0±30]ppm/°C
Dielectric withstanding voltage	2.5 U _{RC} for U _{RC} ≤ 500V _{DC}
	1.6 U _{RC} for U _{RC} = 1,000V _{DC}
	1.5 U _{RC} for U _{RC} = 1,000V _{DC}
Capacitance	at 1MHz for C ≤ 1,000pF
	at 1kHz for C > 1,000pF
Dissipation factor at 25°C	≤ 0.015 (150/C + 7)% at 1MHz for C ≤ 50pF
	≤ 0.15% at 1MHz for 50pF < C ≤ 1,000pF
	≤ 0.15% at 1kHz for C > 1,000pF
Insulation resistance at 25°C	≥ 100,000 MΩ for C ≤ 10nF
	under U _{RC} for U _{RC} ≤ 500V _{DC}
	≥ 1,000 MΩ.μF for C > 10nF under 500V _{DC} for U _{RC} > 500V _{DC}
Aging	None

Description	BX	2C1	X7R
Operating temperature	-55°C to +125°C	-55°C to +125°C	-55°C to +125°C
Climatic category	55 / 125 / 56	55 / 125 / 56	55 / 125 / 56
Rated voltage (U _{RC})	10V _{DC} to 500V _{DC}	10V _{DC} to 500V _{DC}	10V _{DC} to 1,000V _{DC}
Maximum ΔC/°C over temperature range without DC voltage applied	±15%	±20%	±15%
Maximum ΔC/°C over temperature range with rated voltage applied	+15% -25%	+20% -30%	NA
Temperature coefficient with or without DC voltage applied	NA	NA	NA
Dielectric withstanding voltage	2.5 U _{RC}	2.5 U _{RC}	2.5 U _{RC} for U _{RC} ≤ 500V _{DC}
Capacitance	at 1MHz for C ≤ 100pF		
	at 1kHz for C > 100pF		
Dissipation factor at 25°C	≤ 2.5% at 1MHz for C ≤ 100pF		
	≤ 2.5% at 1kHz for C > 100pF		
Insulation resistance at 25°C	≥ 100,000 MΩ for C ≤ 10nF		
	under U _{RC} for U _{RC} ≤ 500V _{DC}		
	≥ 1,000 MΩ.μF for C > 10nF under 500V _{DC} for U _{RC} > 500V _{DC}		
Aging	≤ 2.5% per decade hour		

Low and Medium Voltage Chips Capacitors

CEC / CNC Series

DIMENSIONS in inches (mm)



STANDARD RATINGS

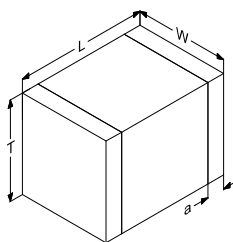
Series		CEC/CNC 19				CEC/CNC 17				CEC/CNC 14			
Size		0402				0403				0603			
Dimensions inches (mm)	L	0.039 ± 0.004 (1 ± 0.1)				0.039 ± 0.004 (1 ± 0.1)				0.063 ± 0.006 (1.6 ± 0.15)			
	W	0.02 ± 0.004 (0.5 ± 0.1)				0.03 ± 0.004 (0.76 ± 0.1)				0.032 ± 0.006 (0.8 ± 0.15)			
	a	0.004 min (0.1) min				0.004 min (0.1) min				0.012 ± 0.008 (0.3 ± 0.2)			
	T max.	0.024 (0.6)				0.032 (0.8)				0.04 (1)			
Dielectric		NPO	BX	2C1	X7R	NPO	BX	2C1	X7R	NPO	BX	2C1	X7R
Min. Cap. value		1pF	68pF			1pF	270pF			1pF	270pF		
Rated voltage (U _{nc})	10V	390pF	15nF	15nF	15nF	1.2nF	47nF	47nF	47nF	3.3nF	120nF	120nF	120nF
	16V	270pF	12nF	12nF	15nF	820pF	39nF	39nF	47nF	2.7nF	120nF	120nF	120nF
	25V	180pF	4.7nF	5.6nF	5.6nF	470pF	15nF	18nF	18nF	1.8nF	56nF	56nF	56nF
	50V	82pF	1.2nF	2.2nF	3.9nF	330pF	3.9nF	5.6nF	12nF	820pF	12nF	18nF	33nF
	63V	68pF	820pF	1.2nF	3.9nF	220pF	2.2nF	3.9nF	12nF	680pF	8.2nF	12nF	33nF
	100V	39pF	330pF	560pF	1.2nF	120pF	1nF	1.8nF	3.3nF	330pF	3.3nF	5.6nF	12nF

Series		CEC/CNC 1					CEC/CNC 2						CEC/CNC 18				CEC/CNC 8			
Size		0504					0805						0907				1005			
Dimensions inches (mm)	L	0.049 ± 0.008 (1.25 ± 0.2)					0.079 ± 0.012 (2 ± 0.3)						0.091 ± 0.012 (2.3 ± 0.3)				0.098 ± 0.012 (2.5 ± 0.3)			
	W	0.039 ± 0.008 (1 ± 0.2)					0.049 ± 0.008 (1.25 ± 0.2)						0.071 ± 0.01 (1.8 ± 0.25)				0.049 ± 0.008 (1.25 ± 0.2)			
	a	0.004 min (0.1) min					0.02 ± 0.012 (0.5 ± 0.3)						0.02 ± 0.012 (0.5 ± 0.3)				0.024 ± 0.016 (0.6 ± 0.4)			
	T max.	0.04 (1)					0.052 (1.3)						0.06 (1.5)				0.052 (1.3)			
Dielectric		NPO	BX	2C1	X7R	NPO	NPO Ext.	BX	2C1	X7R	X7R Ext.	NPO	BX	2C1	X7R	NPO	BX	2C1	X7R	
Min. Cap. value		1pF	270pF			1pF		1nF				1pF	47pF			1pF	33pF			
Rated voltage (U _{DC})	10V	3.3nF	120nF	120nF	120nF	12nF	-	470nF	470nF	470nF	-	18nF	820nF	820nF	820nF	3.3nF	100nF	100nF	100nF	
	16V	3.3nF	120nF	120nF	120nF	12nF	-	470nF	470nF	470nF	-	18nF	680nF	680nF	680nF	3.3nF	100nF	100nF	100nF	
	25V	1.8nF	56nF	56nF	56nF	6.8nF	-	220nF	220nF	220nF	-	12nF	330nF	390nF	390nF	2.2nF	68nF	68nF	68nF	
	50V	1.2nF	15nF	22nF	33nF	3.3nF	-	56nF	82nF	120nF	-	5.6nF	82nF	120nF	150nF	1.8nF	56nF	56nF	56nF	
	63V	820pF	8.2nF	15nF	33nF	2.7nF	-	33nF	47nF	120nF	-	4.7nF	56nF	82nF	120nF	1.8nF	39nF	56nF	56nF	
	100V	390pF	3.3nF	6.8nF	12nF	1.5nF	-	12nF	27nF	39nF	-	2.7nF	22nF	39nF	68nF	1nF	12nF	18nF	18nF	
	Min. Cap. value	-	-			1pF		390pF				1pF	330pF			1pF	330pF			
	200V	-	-	-	-	390pF	820pF	3.3nF	5.6nF	10nF	22nF	680pF	4.7nF	8.2nF	12nF	390pF	3.9nF	5.6nF	6.8nF	
	500V	-	-	-	-	100pF	470pF	-	560pF	1.2nF	5.6nF	180pF	-	1nF	1.5nF	120pF	-	560pF	820pF	
	1,000V	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	

CEC / CNC Series

Low and Medium Voltage Chips Capacitors

DIMENSIONS in inches (mm)



STANDARD RATINGS

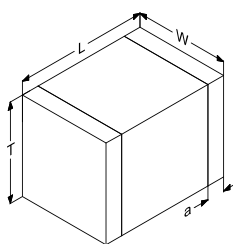
Series		CEC/CNC 12						CEC/CNC 4						CEC/CNC 9				CEC/CNC 3					
Size		1206						1210						1605				1806					
Dimensions inches (mm)	L	0.126 ± 0.016 [3.2 ± 0.4]						0.126 ± 0.016 [3.2 ± 0.4]						0.158 ± 0.02 [4 ± 0.5]				0.177 ± 0.02 [4.5 ± 0.5]					
	W	0.063 ± 0.006 [1.6 ± 0.15]						0.098 ± 0.012 [2.5 ± 0.3]						0.05 ± 0.008 [1.25 ± 0.2]				0.063 ± 0.008 [1.6 ± 0.2]					
	a	0.02 ± 0.012 [0.5 ± 0.3]						0.024 ± 0.016 [0.6 ± 0.4]						0.024 ± 0.016 [0.6 ± 0.4]				0.024 ± 0.016 [0.6 ± 0.4]					
	T max.	0.063 [1.6]						0.071 [1.8]						0.05 [1.25]				0.063 [1.6]					
Dielectric		NPO	NPO Ext.	BX	2C1	X7R	X7R Ext.	NPO	NPO Ext.	BX	2C1	X7R	X7R Ext.	NPO	BX	2C1	X7R	NPO	BX	2C1	X7R		
Min. Cap. value		1pF		1.8nF				10pF		2.2nF				10pF		220pF			47pF		390pF		
Rated voltage (U _{IL})	10V	22nF	-	1.2μF	1.2μF	1.2μF	-	56nF	-	2.2μF	2.2μF	2.2μF	-	6.8nF	150nF	150nF	150nF	12nF	330nF	330nF	330nF		
	16V	22nF	-	820nF	1.2μF	1.2μF	-	56nF	-	2.2μF	2.2μF	2.2μF	-	6.8nF	150nF	150nF	150nF	12nF	330nF	330nF	330nF		
	25V	15nF	-	330nF	680nF	680nF	-	39nF	-	1μF	1μF	1μF	-	4.7nF	100nF	100nF	100nF	8.2nF	220nF	220nF	220nF		
	50V	6.8nF	-	150nF	220nF	270nF	-	18nF	-	330nF	470nF	560nF	-	3.9nF	68nF	82nF	82nF	6.8nF	150nF	180nF	180nF		
	63V	6.8nF	-	100nF	150nF	180nF	-	15nF	-	180nF	270nF	560nF	-	3.3nF	56nF	68nF	82nF	5.6nF	100nF	150nF	180nF		
	100V	3.9nF	-	39nF	68nF	120nF	-	8.2nF	-	82nF	150nF	220nF	-	2.2nF	27nF	27nF	33nF	3.9nF	39nF	56nF	56nF		
	Min. Cap. value	1pF		390pF				10pF		470pF				10pF		470pF			47pF		390pF		
	200V	1.2nF	3.3nF	8.2nF	15nF	27nF	68nF	2.2nF	5.6nF	18nF	33nF	56nF	150nF	820pF	6.8nF	10nF	12nF	1.2nF	8.2nF	12nF	18nF		
	500V	330pF	1.5nF	820pF	2.2nF	3.9nF	12nF	680pF	2.7nF	1.8nF	3.9nF	8.2nF	27nF	220pF	-	1.2nF	1.5nF	330pF	820pF	1.8nF	2.7nF		
	1,000V	120pF	680pF	-	-	560pF	2.7nF	220pF	1nF	-	-	1.2nF	4.7nF	82pF	-	-	-	120pF	-	-	560pF		

Series		CEC/CNC 6							CEC/CNC 70					CEC/CNC 5					CEC/CNC 7					
Size		1812							1825					2210					2220					
Dimensions inches (mm)	L	0.177 ± 0.02 (4.5 ± 0.5)							0.177 ± 0.020 (4.5 ± 0.5)					0.224 ± 0.02 (5.7 ± 0.5)					0.224 ± 0.02 (5.7 ± 0.5)					
	W	0.126 ± 0.016 (3.2 ± 0.4)							0.250 ± 0.020 (6.35 ± 0.5)					0.098 ± 0.012 (2.5 ± 0.3)					0.197 ± 0.02 (5 ± 0.5)					
	a	0.024 ± 0.016 (0.6 ± 0.4)							0.024 ± 0.020 (0.6 ± 0.4)					0.024 ± 0.016 (0.6 ± 0.4)					0.024 ± 0.016 (0.6 ± 0.4)					
	T max.	0.071 (1.8)							0.071 (1.8)					0.067 (1.7)					0.071 (1.8)					
Dielectric		NPO	NPO Ext.	BX	2C1	X7R	X7R Ext.	NPO	BX	2C1	X7R	NPO	BX	2C1	X7R	NPO	NPO Ext.	BX	2C1	X7R	X7R Ext.			
Min. Cap. value		47pF		3.9nF					100pF		1nF			220pF		1nF			100pF		22nF			
Rated voltage (U _R)	10V	82nF	-	4.7μF	4.7μF	4.7μF	-	150nF	4.7μF	4.7μF	4.7μF	39nF	680nF	680nF	680nF	180nF	-	10μF	10μF	10μF	-			
	16V	82nF	-	3.3μF	3.3μF	4.7μF	-	150nF	2.7μF	2.7μF	2.7μF	39nF	680nF	680nF	680nF	180nF	-	8.2μF	8.2μF	10μF	-			
	25V	39nF	-	2.2μF	2.2μF	2.2μF	-	82nF	2.2μF	2.2μF	2.2μF	22nF	470nF	470nF	470nF	82nF	-	4.7μF	4.7μF	4.7μF	-			
	50V	27nF	-	560nF	820nF	1.2μF	-	56nF	1.2μF	1.5μF	1.5μF	18nF	390nF	390nF	390nF	56nF	-	1.2μF	2.2μF	2.7μF	-			
	63V	22nF	-	330nF	470nF	1μF	-	47nF	680nF	1μF	1μF	15nF	330nF	390nF	390nF	47nF	-	820nF	1.5μF	2.7μF	-			
	100V	15nF	-	150nF	270nF	470nF	-	22nF	270nF	560nF	820nF	10nF	100nF	180nF	180nF	33nF	-	270nF	680nF	1μF	-			
	Min. Cap. value	47pF		470pF					82pF		1nF			220pF		1nF			100pF		1.2nF			
	200V	4.7nF	12nF	27nF	47nF	68nF	330nF	8.2nF	56nF	100nF	180nF	3.9nF	27nF	47nF	68nF	10nF	27nF	56nF	120nF	220nF	820nF			
	500V	1.2nF	5.6nF	2.7nF	6.8nF	10nF	82nF	2.2nF	5.6nF	12nF	27nF	1nF	2.7nF	5.6nF	8.2nF	2.7nF	15nF	5.6nF	15nF	27nF	180nF			
	1,000V	470pF	2.7nF	-	-	2.2nF	22nF	820pF	-	-	3.9nF	470pF	-	-	1.8nF	1nF	6.8nF	-	-	3.9nF	39nF			

Low and Medium Voltage Chips Capacitors

CEC / CNC Series

DIMENSIONS in inches (mm)



STANDARD RATINGS

Series		CEC/CNC 71				CEC/CNC W				CEC/CNC X				CEC/CNC 72			
Size		2225				2528				3030				3040			
Dimensions inches (mm)	L	0.224 ± 0.02 [5.7 ± 0.5]				0.250 ± 0.020 [6.35 ± 0.5]				0.299 ± 0.02 [7.6 ± 0.5]				0.299 ± 0.02 [7.6 ± 0.5]			
	W	0.250 ± 0.020 [6.35 ± 0.5]				0.276 ± 0.020 [7 ± 0.5]				0.299 ± 0.02 [7.6 ± 0.5]				0.4 ± 0.02 [10.16 ± 0.5]			
	a	0.024 ± 0.020 [0.6 ± 0.4]				0.024 ± 0.020 [0.6 ± 0.4]				0.024 ± 0.016 [0.6 ± 0.4]				0.024 ± 0.016 [0.6 ± 0.4]			
	T max.	0.079 (2)				0.079 (2)				0.079 (2)				0.079 (2)			
Dielectric		NPO	BX	2C1	X7R	NPO	BX	2C1	X7R	NPO	BX	2C1	X7R	NPO	BX	2C1	X7R
Min. Cap. value		150pF	1.5nF			270pF	2.7nF			390pF	4.7nF			680pF	8.2nF		
Rated voltage [U _{dc}]	10V	180nF	5.6μF	5.6μF	5.6μF	220nF	6.8μF	6.8μF	6.8μF	330nF	10μF	10μF	10μF	470nF	12μF	12μF	12μF
	16V	180nF	3.3μF	3.3μF	4.7μF	220nF	3.9μF	3.9μF	3.9μF	330nF	6.8μF	6.8μF	6.8μF	470nF	8.2μF	8.2μF	8.2μF
	25V	100nF	2.2μF	2.2μF	3.9μF	120nF	2.7μF	2.7μF	2.7μF	180nF	3.9μF	3.9μF	3.9μF	270nF	5.6μF	5.6μF	5.6μF
	50V	68nF	1.2μF	1.5μF	2.2μF	82nF	1.5μF	1.8μF	1.8μF	120nF	2.7μF	2.7μF	2.7μF	150nF	3.3μF	3.9μF	3.9μF
	63V	56nF	820nF	1.2μF	1.5μF	68nF	1μF	1.5μF	1.8μF	100nF	1.5μF	2.2μF	2.2μF	120nF	2.2μF	2.7μF	3.3μF
	100V	33nF	390nF	680nF	1.2μF	33nF	390nF	820nF	1.2μF	56nF	680nF	1.2μF	1.5μF	82nF	1μF	1.8μF	2.2μF
	200V	12nF	68nF	120nF	270nF	15nF	82nF	150nF	270nF	22nF	150nF	270nF	470nF	33nF	180nF	390nF	560nF
	500V	3.3nF	5.6nF	15nF	33nF	3.9nF	8.2nF	18nF	33nF	6.8nF	12nF	33nF	68nF	8.2nF	22nF	56nF	100nF
	1,000V	1.2nF	-	-	4.7nF	1.5nF	-	-	5.6nF	2.7nF	-	-	10nF	3.3nF	-	-	15nF

Available capacitance values:

NPO: E6, E12, E24, E48, E96 (see page 14). Specific values upon request.

X7R: E6, E12, E24 (see page 14). Specific values upon request.

The above table defines the standard products, other components may be built upon request.

Other temperature coefficients, temperature characteristic 2B1 and Bismuth free dielectrics are available: contact your sales representative.

General Information NPO/COG (Class 1)

COMPOSITION

NPO capacitors are produced by using a dielectric made of titanium dioxide (TiO_2) modified by magnesium oxide MgO (white ceramics) or a rare earth oxide, e.g. Nd_2O_3 (other NPO ceramics).

As a consequence, these ceramics are non ferro-electric materials with a low dielectric constant ($\epsilon_r \leq 110$).

Other additives are used to dope the dielectric constant up to 300. Though derogating from CG class, doped dielectric constant features a linear temperature drift and a matchless stability compared with class 2 ceramics.

The wide range of possible NPO dielectric compositions enables to use the material best suited to the application :

- standard applications,
- high voltage,
- high temperature,
- microwave,
- power capacitors.

«Temperature coefficient» compositions are particularly suitable for impedance matching. These ceramics usually enable to achieve temperature coefficients from 0 to $-1\,000\text{ ppm}/^\circ\text{C}$. For specific requirements, other coefficients can be achieved (e.g. $-3\,300\text{ ppm}/^\circ\text{C}$).

STABILITY

As ϵ_r is low, these dielectrics are extremely stable with only minor changes under such stresses as :

- temperature,
- voltage,
- frequency.

In addition, they are not affected by piezo-electric phenomena and their dielectric absorption coefficients are low and even non measurable for dielectrics with the lowest constants.

MECHANICAL PROPERTIES

Class 1 ceramics are the perfect match for metallic electrodes made of Pd or Ag-Pd alloy and have a high hardness and mechanical toughness making them resistant to thermal shocks (wave soldering for instance) and to thermal cycling after mounting on substrates having an expansion coefficient close to the capacitor one.

Ceramic chips meet CECC 32100 and NF C 93133 standards.

CLIMATIC CATEGORIES

Climatic categories are identified by three-digit codes as per NF C 20700 standard. Coding method is described in table 6.

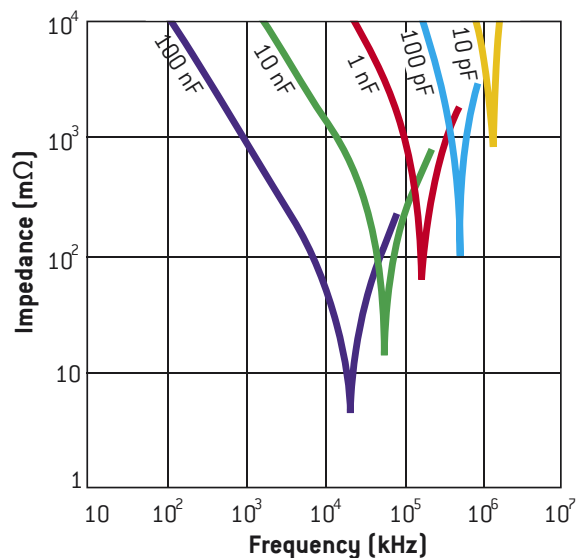
e.g. : $-55^\circ\text{C} + 125^\circ\text{C} / 56$ days category is identified by code 434.

TEMPERATURE COEFFICIENT

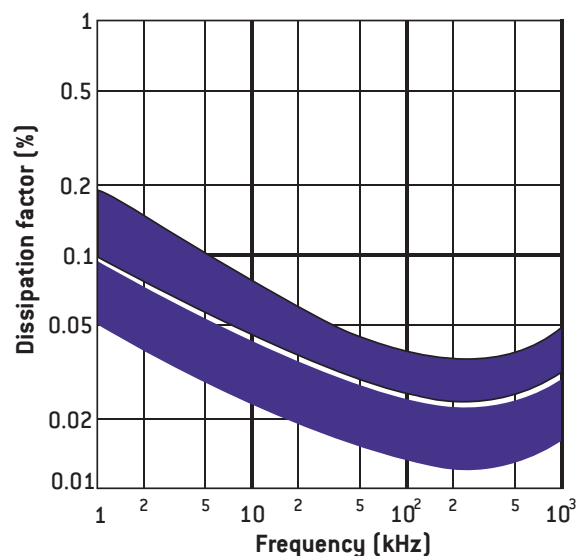
Temperature coefficient $k\theta$ (ppm/ $^\circ\text{C}$)		
$k\theta$	Tolerances	Code letter
+ 100	± 30	AG
0	± 30	CG
- 33	± 30	HG
- 75	± 30	LG
- 150	± 30	PG
- 220	± 30	RG
- 330	± 60	SH
- 470	± 60	TH
- 750	± 120	UJ
- 1 000	± 250	QK

General Information NPO/COG (Class 1)

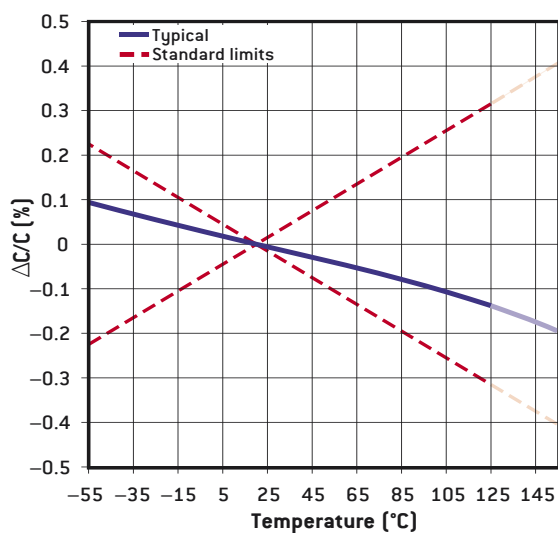
IMPEDANCE VERSUS FREQUENCY



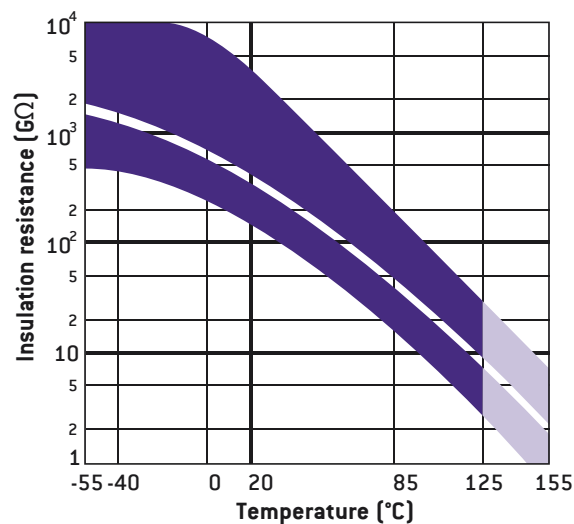
DISSIPATION FACTOR VERSUS FREQUENCY



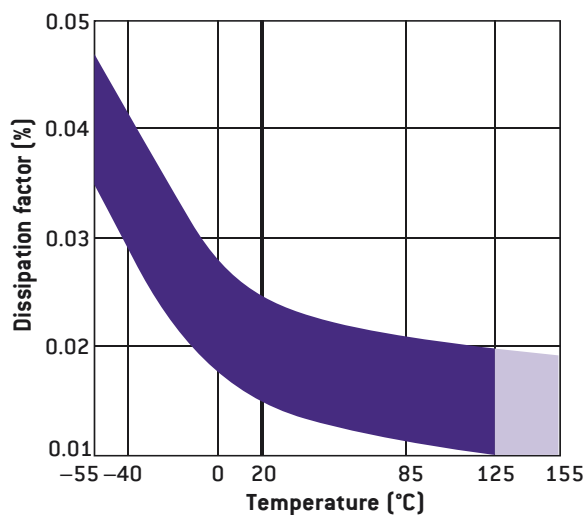
CAPACITANCE CHANGE VERSUS TEMPERATURE



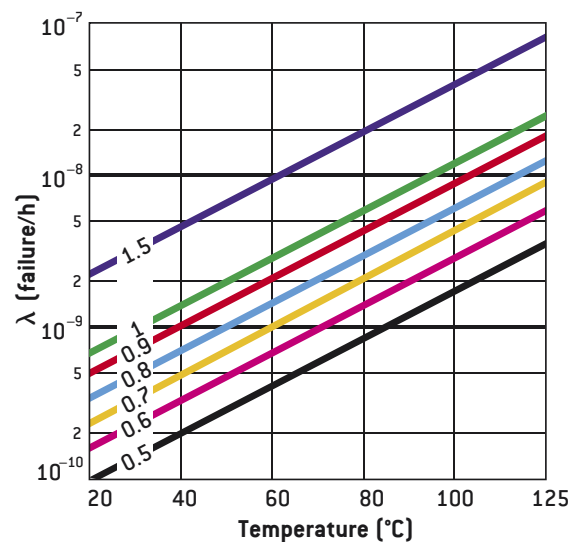
IR VERSUS TEMPERATURE



DISSIPATION FACTOR VERSUS TEMPERATURE



TYPICAL FAILURE RATE VERSUS TEMPERATURE



General Information X7R (Class 2)

COMPOSITION

Class 2 capacitors are produced by using a dielectric made of barium titanate (Ba Ti O_3). By nature, the dielectric is a ferroelectric compound with a high dielectric constant usually varying :

- from 1 000 to 5 000 - typical of capacitors meeting 2C1 type specifications (BX, X7R),
- from 5 000 to 15 000 - typical of capacitors meeting Z5U or Y5V type specifications.

Depending on whether the dielectric contains a flux additive, mainly bismuth or boron, electrodes are made of Ag-Pd alloys with high silver content or high palladium content, even pure palladium in some cases.

STABILITY

As the dielectric is a ferro-electric material, class 2 capacitors present significant variations under such stresses as :

- temperature,
- voltage,
- frequency.

In addition, the dielectric absorption coefficient can reach a few % and piezo-electric phenomena can affect the dielectric at critical frequencies (full information and specific documents available on request).

MECHANICAL PROPERTIES

Class 2 dielectrics are hard materials and are sensitive to thermo-mechanical stress. Stress should be limited when mounting and adequate substrates with an adapted expansion coefficient used.

BISMUTH OR BISMUTH FREE DIELECTRICS

Class 2 capacitors are made of ceramics capable to embed a flux element (e.g. bismuth or boron salt). Their eventual use will affect the choice of electrode alloys firing temperature used. Capacitor behavior under such constraints as temperature, voltage, frequency and even reliability, in some applications (further information available on request), is also different.

That is why French and European standard authorities have decided to differentiate bismuth from bismuth free ceramics by measuring tangent δ at -55°C . Tangent $\text{Tg } \delta$ (-55°C) 350.10^{-4} in flux free dielectrics.

Flux free dielectrics are identified by suffix «A» after capacitor type (e.g. CNC2A).

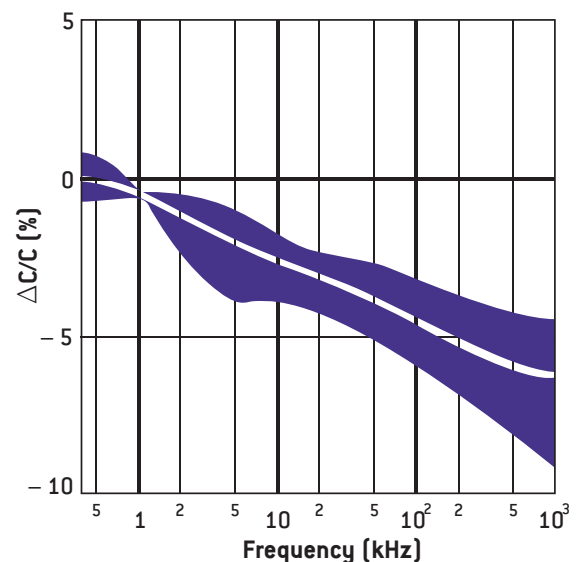
CAPACITANCE/TEMPERATURE RELATIONSHIP

Capacitance variations are defined within a specified temperature range, + 20°C being the reference temperature. This characteristic is expressed by associating the temperature range and capacitance stability.

Stability category Code letter	Max. capacitance variation (%) with reference to capacitance at 20°C	
	Without voltage	At rated DC voltage (U_{DC})
B	± 10	+ 10 – 15
C	± 20	+ 20 – 30
D	+ 20 – 30	+ 20 – 40
E	+ 20 – 55	+ 20 – 65
R	+ 15 – 15	Not applicable
X	+ 15 – 15	+ 15 – 25

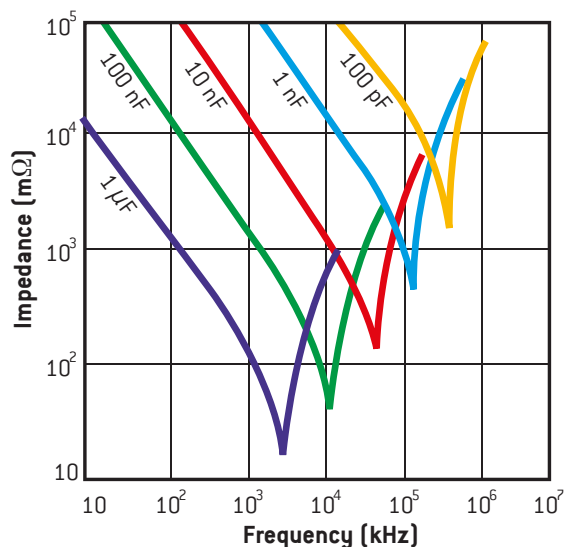
Temperature category	
Code	Temperature range
1	$-55^\circ\text{C} + 125^\circ\text{C}$
2	$-55^\circ\text{C} + 85^\circ\text{C}$
4	$-25^\circ\text{C} + 85^\circ\text{C}$

CAPACITANCE CHANGE VERSUS FREQUENCY

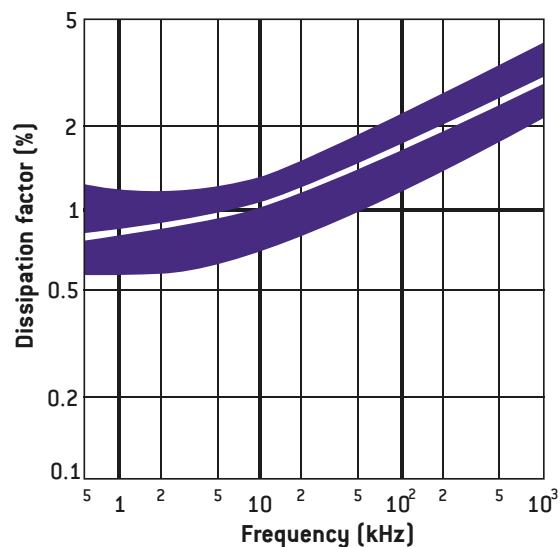


General Information X7R (Class 2)

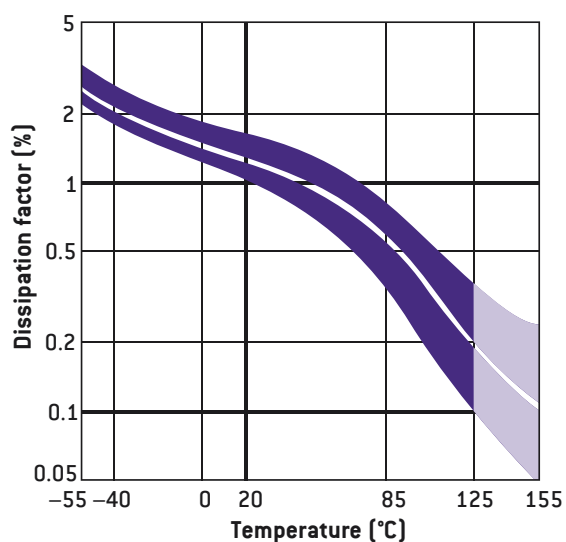
IMPEDANCE VERSUS FREQUENCY



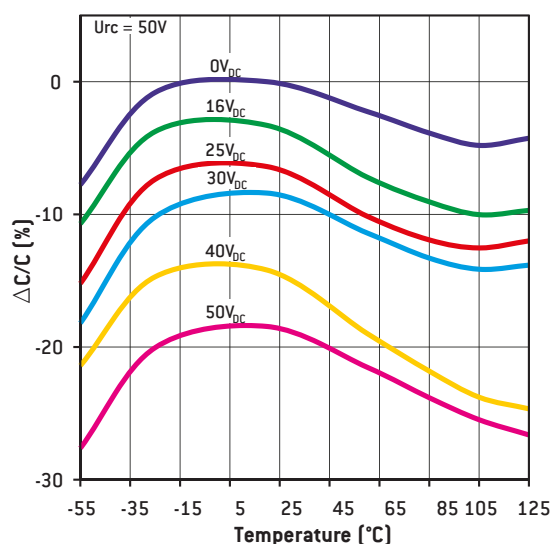
DISSIPATION FACTOR VERSUS FREQUENCY



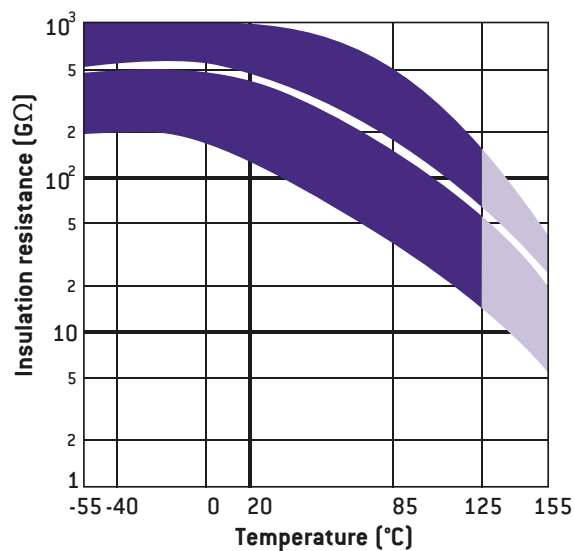
DISSIPATION FACTOR VERSUS TEMPERATURE



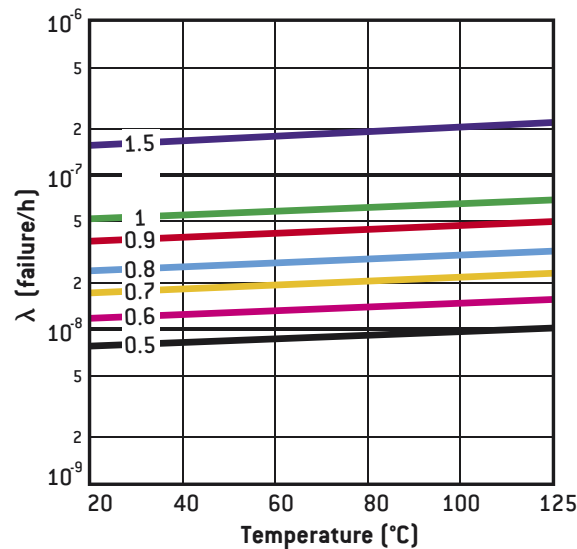
CAPACITANCE CHANGE VERSUS TEMPERATURE



IR VERSUS TEMPERATURE

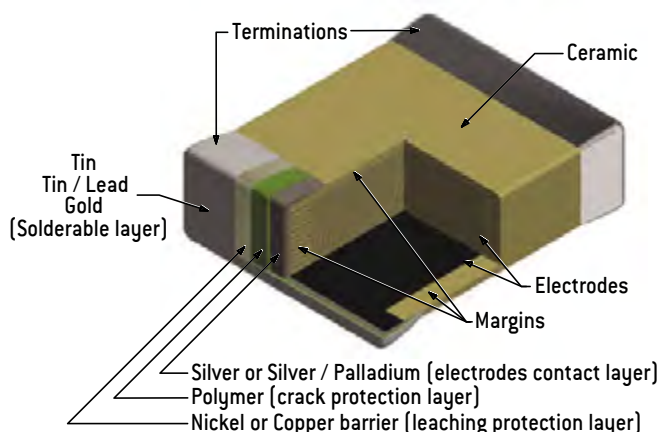


TYPICAL FAILURE RATE VERSUS TEMPERATURE



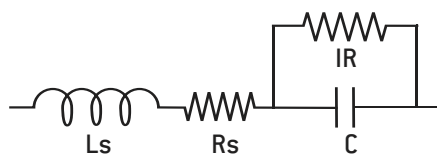
Ceramic Capacitors Technology

MLCC STRUCTURE



EQUIVALENT CIRCUIT

Capacitor is a complex component combining resistive, inductive and capacitive phenomena. A simplified schematic for the equivalent circuit is:



DIELECTRIC CHARACTERISTICS

Insulation Resistance (IR) is the resistance measured under DC voltage across the terminals of the capacitor and consists principally of the parallel resistance shown in the equivalent circuit. As capacitance values and hence the area of dielectric increases, the IR decreases and hence the product $[C \times IR]$ is often specified in $\Omega \cdot F$ or $M\Omega \cdot \mu F$.

The Equivalent Series Resistance (ESR) is the sum of the resistive terms which generate heating when capacitor is used under AC voltage at a given frequency f .

Dissipation factor (DF) is the ration of the apparent power input will turn to heat in the capacitor:

$$DF = 2\pi f C ESR$$

When a capacitor works under AC voltage, **heat power loss (P)**, expressed in Watt, is equal to:

$$P = 2\pi f C V_{rms}^2 DF$$

The series inductance (L_s) is due to the currents running through the electrodes. It can distort the operation of the capacitor at high frequency where the **impedance (Z)** is given as:

$$Z = R_s + j [L_s \cdot \omega - 1/(C \cdot \omega)] \text{ with } \omega = 2\pi f$$

When frequency rises, the capacitive component of capacitors is gradually canceled up to the resonance frequency, where :

$$Z = R_s \text{ and } L_s C \cdot \omega^2 = 1$$

Above this frequency the capacitor behaves like an inductor.

	P100	NPO	N2200 [C4xx]	BX	2C1	X7R
Dielectric material	Porcelain	Magnesium titanate or Neodynum baryum titanate	Barium zirconate titanate	Baryum titanate [BaTiO ₃]		
Dielectric constant	15 – 18	20 – 85	450	2,000 – 5,000		
Electrode technology	PME (Precious Metal Electrodes): Ag/Pd					
Capacitance variation between –55°C and +125/°C without DC voltage	{100±30}ppm/°C	{0±30}ppm/°C	{–2,200±500}ppm/°C	±15%	±20%	±15%
Capacitance variation between –55°C and +125/°C with DC rated voltage			0 -15%	15% –25%	20% –30%	Not applicable
Piezo-electric effect	None		None	Yes		
Dielectric absorption	None		Few %	Few %		
Thermal shock sensitive	+		+	++		

Ceramic Capacitors Technology

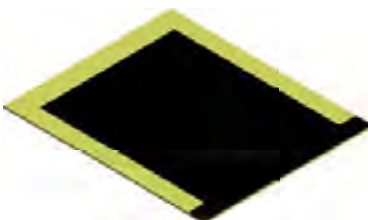
MANUFACTURING STEPS

SLIP CASTING



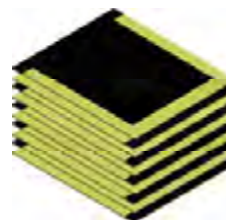
A slurry, a mix of ceramic powder, binder and solvents, is poured onto conveyor belt inside a drying oven, resulting in a dry ceramic sheet.

ELECTRODE SCREEN PRINTING



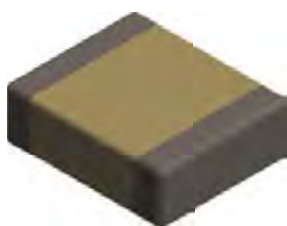
The electrode ink, made from a metal powder mixed with solvents, is printed onto the ceramic sheets using a screen printing process.

STACKING



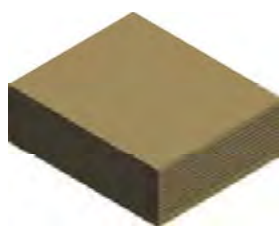
The sheets with electrode printed are stacked to create a multilayer structure.

TERMINATIONS



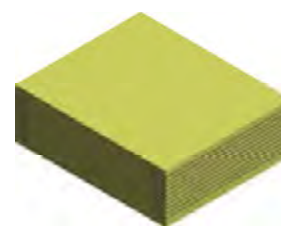
Each terminal of the capacitor is dipped in the termination ink, mix of metal powder, solvents and glass frit and the parts are fired in an oven.

SINTERING



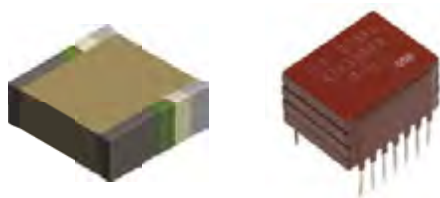
The parts are sintered in an oven with a precise temperature profile which is very important to the characteristics of the capacitors.

PRESSING



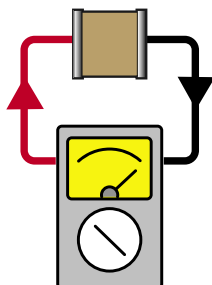
Pressure is applied to the stack to fuse all the separate layers, this created a monolithic structure.

TERMINATIONS PLATING



Stacking + leads soldering + encapsulation
[see pages 10-11]

FINAL TESTING



PACKAGING



User Guide

SMD TERMINATIONS

NON RoHS COMPLIANT	Code	RoHS COMPLIANT	Code	Recommended mounting process							Storage (months)*
				Magnetic	Epoxy bonding	Iron soldering	Wave soldering	Vapor phase soldering	Infrared soldering	Wire bonding	
Ag	Q	Ag	QW / P	No	•	•	•	•			18
Ag/Pd/Pt	-	Ag/Pd/Pt	W / A	No	•	•	•				24
Ag/Pd/Pt + dipped Sn/Pb 60/40	H	Ag/Pd/Pt + dipped Sn	HW	No		•					24
Ag + Ni + electrolytic Sn/Pb 95/5	C	Ag + Ni + electrolytic Sn	CW / S	Yes		•	•	•	•		18
Ag + Ni + electrolytic Sn/Pb 60/40	D	-	-	Yes		•	•	•	•		18
-	-	Ag + Cu + electrolytic Sn	C**	No		•	•	•	•		18
Ag + Ni + dipped Sn/Pb 60/40	E	-	-	Yes		•	•				24
Ag + Ni + Au	G	Ag + Ni + Au	GW	Yes	•	•	•	•	•	•	36
Ag + Polymer + Ni + Sn/Pb 95/5	YC	Ag + Polymer + Ni + Sn	YCW	Yes		•	•	•	•		18
Ag + Polymer + Ni + Sn/Pb 60/40	YD	-	-	Yes		•	•	•	•		18
Ag + Polymer + Ni + Au	YG	Ag + Polymer + Ni + Au	YGW	Yes	•	•	•	•	•	•	36

Nickel (Ni) or Copper (Cu) barriers amplify thermal shock and are not recommended for chip sizes larger than 3030.

* Storage must be in a dry environment at a temperature of 20°C with a relative humidity below 50%, or preferably in a package enclosing a desiccant.

** Non magnetic chips series only.

SMD ENVIRONMENTAL TESTS

Ceramic chip capacitors for SMD are designed to meet test requirements of **CECC 32100** and **NF C 93133** standards as specified below in compliance with **NF C 20700** and **IEC 68** standards:

- Solderability: **NF C 20758**, 260°C, bath 62/36/2.
- Adherence: 5N force.
- Vibration fatigue test: **NF C 20706**, 20 g, 10 Hz to 2,000 Hz, 12 cycles of 20 minutes each.
- Rapid temperature change: **NF C 20714**, -55°C to + 125°C, 5 cycles.
- Combined climatic test: **IEC 68-2-38**.
- Damp heat: **NF C 20703**, 93 %, H.R., 40°C.
- Endurance test: 1,000 hours, 1.5 U_{RC}, 125°C.

STORAGE OF CHIP CAPACITORS

TINNED OR NON TINNED CHIP CAPACITORS

Storage must be in a dry environment at a temperature of 20°C with a relative humidity below 50 %, or preferably in a packaging enclosing a desiccant.

STORAGE IN INDUSTRIAL ENVIRONMENT:

- 2 years for tin dipped chip capacitors,
- 18 months for tin electroplated chip capacitors,
- 2 years for non tinned chip capacitors,
- 3 years for gold plated chip capacitors.

STORAGE IN CONTROLLED NEUTRAL NITROGEN ENVIRONMENT:

- 4 years for tin dipped or electroplated chip capacitors,
- 4 years for non tinned chip capacitors,
- 5 years for gold plated chip capacitors.

Storage duration should be considered from delivery date and not from batch manufacture date. The tests carried out at final acceptance stage (solderability, susceptibility to solder heat) enable to assess the compatibility to surface mounting of the chips.

User Guide

LEAD STYLES

SURFACE MOUNTING

DIL LEADS

P style



PL style



L style



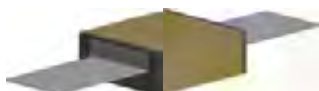
J style



RIBBON LEADS

Micro-strip (type 1)
Short Micro-strip (type 1S)

Axial (Type 2)



Radial (Type 3)



R style



RX style



RJ style



Please contact Exxelia sales for any lead configuration not shown.

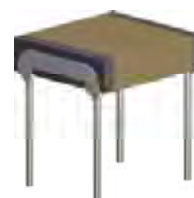
TROUGH-HOLE MOUNTING

AXIAL AND RADIAL

Radial leads (Type 6)



Radial leads (4 leads)



Axial leads (Type 7)



DIL leads: N style



ENCAPSULATION STYLES

Ceramic encapsulation
(selfprotected)

Varnish



Conformal coating

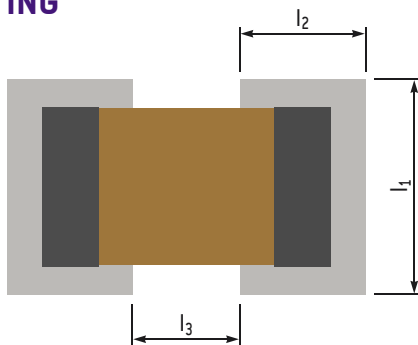


Molding



User Guide

SOLDERING ADVICES FOR REFLOW SOLDERING



Large chips above size 2225 are not recommended to be mounted on epoxy board due to thermal expansion coefficient mismatch between ceramic capacitor and epoxy. Where larger sizes are required, it is recommended to use components with ribbon or other adapted leads so as to absorb thermo-mechanical strains.

Dimensions in inches (in mm)	Reflow soldering						Wave soldering					
	l ₁		l ₂		l ₃		l ₁		l ₂		l ₃	
0402	0.043	(1.1)	0.035	(0.9)	0.012	(0.3)	0.043	(1.1)	0.047	(1.2)	0.012	(0.3)
0403	0.055	(1.4)	0.035	(0.9)	0.012	(0.3)	0.055	(1.4)	0.047	(1.2)	0.012	(0.3)
0504	0.063	(1.6)	0.051	(1.3)	0.016	(0.4)	0.063	(1.6)	0.063	(1.6)	0.016	(0.4)
0603	0.055	(1.4)	0.059	(1.5)	0.02	(0.5)	0.055	(1.4)	0.071	(1.8)	0.02	(0.5)
0805	0.073	(1.85)	0.065	(1.65)	0.024	(0.6)	0.073	(1.85)	0.077	(1.95)	0.024	(0.6)
0907	0.094	(2.4)	0.065	(1.65)	0.035	(0.9)	0.094	(2.4)	0.077	(1.95)	0.035	(0.9)
1005	0.073	(1.85)	0.067	(1.7)	0.039	(1)	0.073	(1.85)	0.079	(2)	0.039	(1)
1206	0.083	(2.1)	0.067	(1.7)	0.059	(1.5)	0.083	(2.1)	0.079	(2)	0.059	(1.5)
1210	0.118	(3)	0.069	(1.75)	0.059	(1.5)	0.118	(3)	0.081	(2.05)	0.059	(1.5)
1605	0.073	(1.85)	0.071	(1.8)	0.087	(2.2)	0.073	(1.85)	0.083	(2.1)	0.087	(2.2)
1806	0.087	(2.2)	0.073	(1.85)	0.102	(2.6)	0.087	(2.2)	0.085	(2.15)	0.102	(2.6)
1812	0.152	(3.85)	0.073	(1.85)	0.102	(2.6)	0.152	(3.85)	0.085	(2.15)	0.102	(2.6)
1825	0.281	(7.15)	0.073	(1.85)	0.102	(2.6)	0.281	(7.15)	0.085	(2.15)	0.102	(2.6)
2210	0.13	(3.3)	0.079	(2)	0.146	(3.7)	0.13	(3.3)	0.091	(2.3)	0.146	(3.7)
2220	0.228	(5.8)	0.079	(2)	0.146	(3.7)	0.228	(5.8)	0.091	(2.3)	0.146	(3.7)
2225	0.281	(7.15)	0.079	(2)	0.146	(3.7)	0.281	(7.15)	0.091	(2.3)	0.146	(3.7)

RECOMMENDED FOOTPRINT FOR SMD CAPACITORS

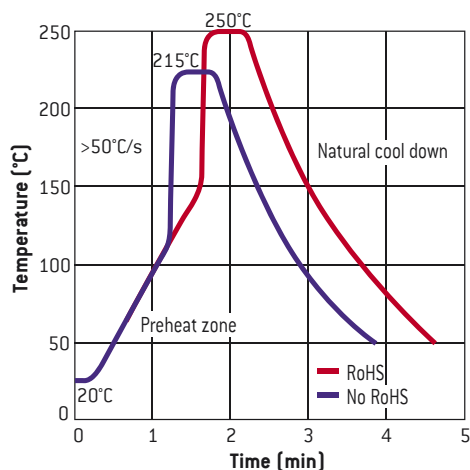
Ceramic is by nature a material which is sensitive both thermally and mechanically. Stresses caused by the physical and thermal properties of the capacitors, substrates and solders are attenuated by the leads.

Wave soldering is unsuitable for sizes larger than 2220 and for the higher ends of capacitance ranges due to possible thermal shock (capacitance values given upon request).

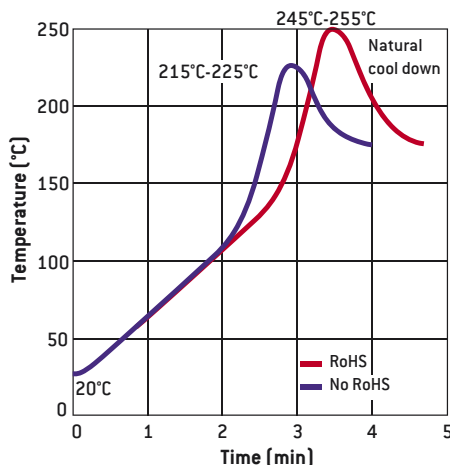
Infrared and vapor phase reflow, are preferred for high reliability applications as inherent thermo-mechanical strains are lower than those inherent to wave soldering.

Whatever the soldering process is, it is highly recommended to apply a thermal cycle, see hereafter our recommended soldering profile:

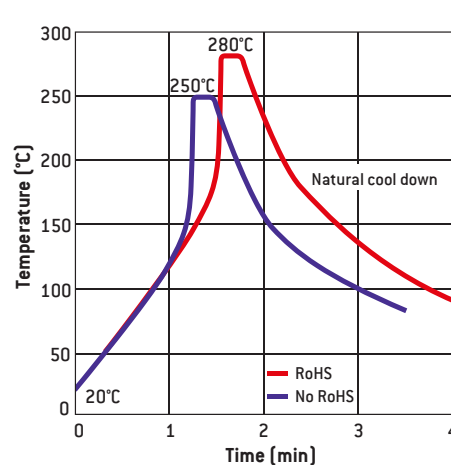
RECOMMENDED VAPOR PHASE REFLOW PROFILE



RECOMMENDED IR REFLOW PROFILE



RECOMMENDED WAVE SOLDERING PROFILE



SOLDERING ADVICES FOR IRON SOLDERING

Attachment with a soldering iron is discouraged due to ceramic brittleness and the process control limitations. In the event that a soldering iron must be used, the following precautions should be observed:

- Use a substrate with chip footprints big enough to allow putting side by side one end of the capacitor and the iron tip without any contact between this tip and the component,
- place the capacitor on this footprint,

- heat the substrate until the capacitor's temperature reaches 150°C minimum (preheating step, maximum 1°C per second),
- place the hot iron tip (a flat tip is preferred) on the footprint **without touching the capacitor**. Use a regulated iron with a 30 watts maximum power. The recommended temperature of the iron is 270 ±10°C. The temperature gap between the capacitor and the iron tip must not exceed 120°C,

User Guide

- leave the tip on the footprint for a few seconds in order to increase locally the footprint's temperature,
- use a cored wire solder and put it down on the iron tip. In a preferred way use Sn/Pb/Ag 62/36/2 alloy,
- wait until the solder fillet is formed on the capacitor's termination,
- take away iron and wire solder,
- wait a few minutes so that the substrate and capacitor come back down to

the preheating temperature,

- solder the second termination using the same procedure as the first,
- let the soldered component cool down slowly to avoid any thermal shock.

PACKAGING

TAPE AND REEL

The films used on the reels correspond to standard IEC 60286-3. Films are delivered on reels in compliance with document IEC 286-3 dated 1991.

Minimum quantity is 250 chips.

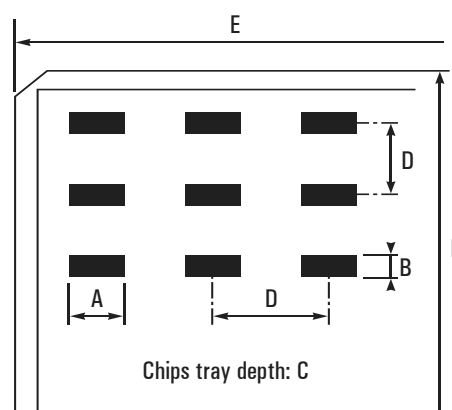
Maximum quantities per reel are as follows:

- Super 8 reel - Ø 180: 2,500 chips.
- Super 8 reel - Ø 330: 10,000 chips.
- Super 12 reel - Ø 180: 1,000 chips.

Reel marking complies with CECC 32100 standard:

- Model.
- Rated capacitance.
- Capacitance tolerance.
- Rated voltage.
- Batch number.

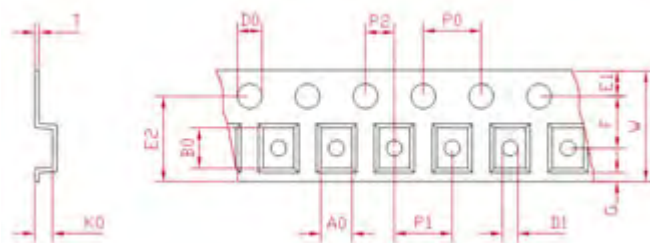
TRAY PACKAGES



DIMENSIONAL CHARACTERISTICS OF CHIPS TRAY PACKAGES

Sizes	Nr. of chips/ package	Oriented chips	Dimensions in inches (in mm)				
			A	B	C	D	E
0402	100	No	0.0112 (0.302)		0.065 (1.65)	0.167 (4.24)	2 (50.8)
0403	100	No	0.0112 (0.302)		0.065 (1.65)	0.167 (4.24)	2 (50.8)
0504	100	Yes	0.059 (1.5)	0.045 (1.14)	0.035 (0.89)	0.167 (4.24)	2 (50.8)
0603	340	Yes	0.1 (2.54)	0.06 (1.52)	0.045 (1.14)	0.167 (4.24)	2 (50.8)
0805	100	Yes	0.1 (2.54)	0.06 (1.52)	0.045 (1.14)	0.167 (4.24)	2 (50.8)
1206	100	No	0.14 (3.56)	0.14 (3.56)	0.06 (1.52)	0.167 (4.24)	2 (50.8)
1210	100	Yes	0.14 (3.56)	0.14 (3.56)	0.06 (1.52)	0.167 (4.24)	2 (50.8)
1812	100	No	0.25 (6.35)	0.25 (6.35)	0.13 (3.3)	0.345 (8.76)	4 (101.6)
2220	25	Yes	0.24 (6.1)	0.265 (6.73)	0.07 (1.78)	0.345 (8.76)	2 (50.8)
	100	Yes	0.25 (6.35)	0.25 (6.35)	0.13 (3.3)	0.345 (8.76)	4 (101.6)
	25	Yes	0.24 (6.1)	0.265 (6.73)	0.07 (1.78)	0.345 (8.76)	2 (50.8)

HIGH Q CAPACITORS TAPE AND REEL PACKAGING SPECIFICATIONS



Sizes	Type (1)	W±0.3 inches (mm)	F±0.05 inches (mm)	P1±0.1 inches (mm)	T max. inches (mm)	Reel Size inches (mm)	Quantity per Reel
A (0505)	H	0,315 (8)	0,138 (3.5)	0,157 (4)	0,010 (0,25)	7,087 (180)	3'000
A (0505)	V	0,315 (8)	0,138 (3.5)	0,157 (4)	0,010 (0,25)	7,087 (180)	3'000
S (0603)	H	0,315 (8)	0,138 (3.5)	0,157 (4)	0,016 (0,4)	7,087 (180)	4'000
F (0805)	H	0,315 (8)	0,138 (3.5)	0,157 (4)	0,016 (0,4)	7,087 (180)	4'000
B (1111)	H	0,315 (8)	0,138 (3.5)	0,157 (4)	0,012 (0,3)	7,087 (180)	1'000
B (1111)	V	0,315 (8)	0,138 (3.5)	0,157 (4)	0,010 (0,25)	7,087 (180)	1'000
X (2225)	H	0,472 (12)	0,138 (5.5)	0,472 (12)	0,018 (0,45)	12,992 (330)	500
E (4040)	H	0,945 (24)	0,453±0,004 (11.5±0.1)	0,630 (16)	0,018 (0,45)	12,992 (330)	700
E (4040)	V	1,260 (32)	0,559±0,004 (14.2±0.1)	0,945 (24)	0,022 (0,55)	15 (381)	350

(1): Horizontal (H) or Vertical (V) orientation in cavities.

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EIA STANDARD CAPACITANCE VALUES

Following EIA standard, the values and multiples that are indicated in the chart below can be ordered. E48, E96 series and intermediary values are available upon request.

E6 (± 20%)	E12 (± 10%)	E24 (± 5%)
10	10	10
		11
		12
15	12	13
		15
		16
22	15	18
		20
		22
33	18	24
		27
		30
47	22	33
		36
		39
68	27	43
		47
		51
100	33	56
		62
		68
150	39	75
		82
		91

Voltage (V)	Code	Letter code
25	250	A
40	400	B
50	500	C
63	630	D
100	101	E
200	201	G
250	251	H
400	401	K
500	501	L
1,000	102	M
2,000	202	P
3,000	302	R
4,000	402	S
5,000	502	T
7,500	752	U
10,000	103	W

EIA CAPACITANCE CODE

The capacitance is expressed in three digit codes and in units of pico Farads (pF). The first and second digits are significant figures of the capacitance value and the third digit identifies the multiplier.

For capacitance value < 10pF, R designates a decimal point.

See examples below:

EIA code	Capacitance value		
	in pF	in nF	in µF
2R2	2.2	0.0022	0.0000022
6R8	6.8	0.0068	0.0000068
220	22	0.022	0.000022
470	47	0.047	0.000047
181	180	0.18	0.00018
221	220	0.22	0.00022
102	1,000	1	0.001
272	2,700	2.7	0.0027
123	12,000	12	0.012
683	68,000	68	0.068
124	120,000	120	0.12
564	560,000	560	0.56
335	3,300,000	3,300	3.3
825	8,200,000	8,200	8.2
156	15,000,000	15,000	15
686	68,000,000	68,000	68
107	100,000,000	100,000	100
227	220,000,000	220,000	220

PART MARKING TOLERANCE CODES

Use the following tolerance code chart for part markings:

Tolerance	Letter code
±0.25pF	CU
±0.5pF	DU
±1pF	FU
±1%	F
±2%	G
±5%	J
±10%	K
±20%	M

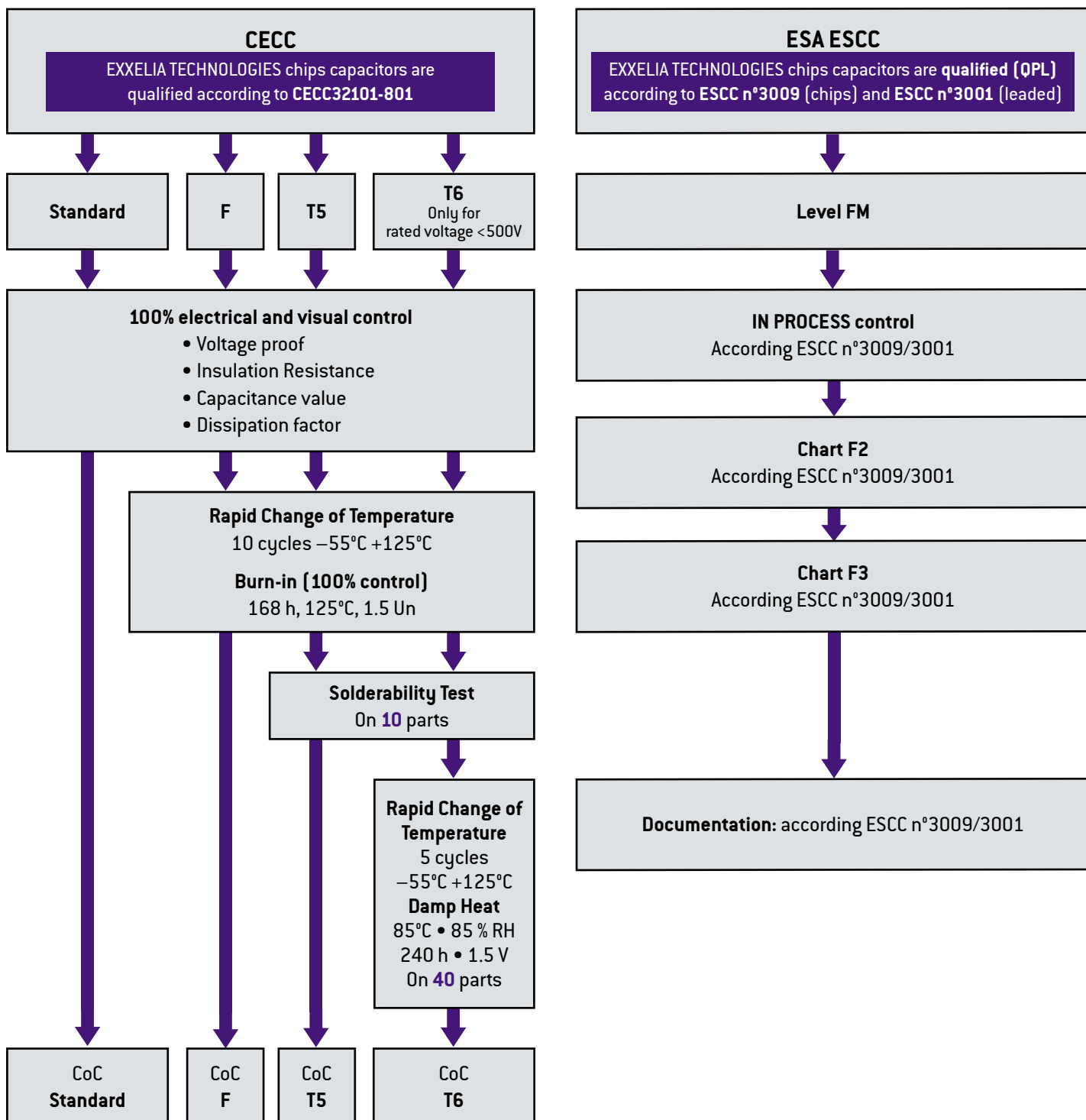
PART MARKING VOLTAGE CODES

Use the following voltage code chart for part markings:

User Guide

RELIABILITY LEVELS

Exxelia proposes different reliability levels for the ceramic capacitors for both NPO and X7R ceramics.



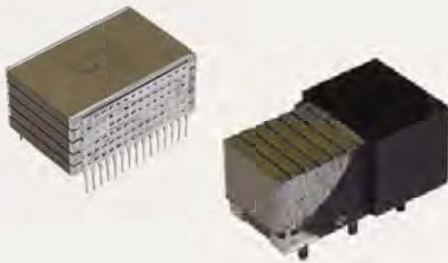
As the world's leading manufacturer of specific passive components, we stand apart through our ability to quickly evaluate the application specific engineering challenges and provide a cost-effective and efficient solutions.

For requirements that cannot be met by catalog products, we offer leading edge solutions in custom configuration: custom geometries, packaging, characteristics, all is possible thanks to our extensive experience and robust development process, while maintaining the highest level of reliability.

Where necessary, special testing is done to verify requirements, such as low dielectric absorption, ultra-high insulation resistance, low dissipation factor, stability under temperature cycling or under specified environmental conditions, etc.

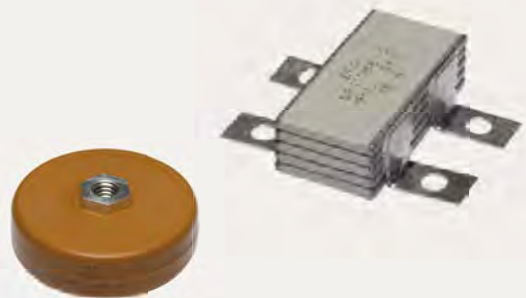
HIGH CAPACITANCE

- High energy density
- Specific case sizes
- Specific shape of connections (high resistance to vibrations)



HIGH VOLTAGE

- Up to 50 kV
- Specific circular shape



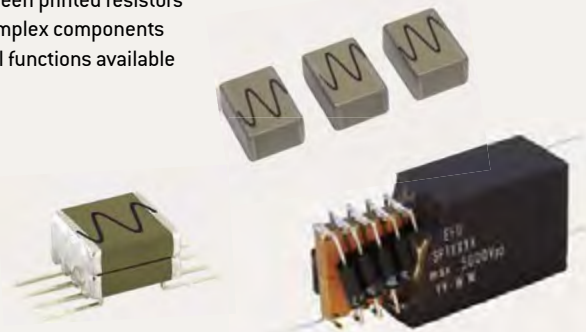
HIGH TEMPERATURE

- Up to 250°C
- Specific shape of connections
- 2,000 hours life time
- HMP soldering



OTHERS

- Screen printed resistors
- Complex components
- Full functions available



General Information

MATERIALS EXPERT

For 50 years and as a market leader, EXXELIA's comprehensive knowledge of the materials properties and performances have enabled us to design capacitors in Porcelain, NPO, BX, 2C1, BP, X7R and –2200ppm/°C ceramics.

CUSTOM DESIGNS

Our catalog products don't meet your application?

Based on the valuable experience accumulated over the design of 2,000+ specific ceramic capacitors, you can trust EXXELIA to define a qualitative custom solution in a time effective manner.

NO OBSOLESCENCE

Choosing a standard or custom EXXELIA product means you won't have to worry about obsolescence.

TYPICAL APPLICATIONS

- Aerospace & Defense: cockpit panels, flight control, radio systems, missile guidance systems...
- Space: military and commercial satellites, launcher...
- Medical: MRI, external defibrillators, implantable devices...
- Telecommunications: base stations...
- Oil and gas: drilling tools, MWD, LWD, wellheads...

ISO 9001 AND AS9100C

Quality is at the core of Exxelia's corporate culture. Each sites has its own certifications.

CERTIFICATIONS

Capacitors manufactured by EXXELIA comply with American and European standards and meet the requirements of many international standards. For Space qualified parts (ESA QPL), please refer to our catalog «Ceramic capacitors for Space applications».

QUALITY & RELIABILITY

EXXELIA is committed to design and manufacture high quality and reliability products. The test cycles reproducing the most adverse operating conditions over extended periods (up to 10 000 hours) have logged to date well over 5.10^9 hours/°Component.

Failure rate data can be provided upon request.

CONFLICT MINERALS

EXXELIA is committed to an approach based on «Conflict Minerals Compliance». This US SEC rule demands complete traceability and a control mechanism for the mineral procurement chain, encouraging importers to buy only «certified» ore.

We have discontinued relations with suppliers that procure from the Democratic Republic of the Congo or an adjoining country.

ENVIRONMENT

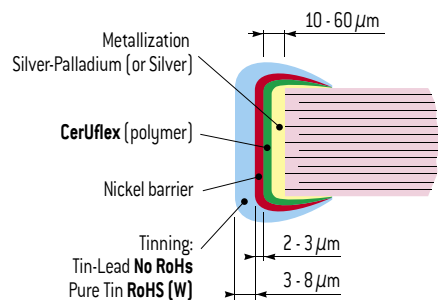
EXXELIA is committed to applying a robust environmental policy, from product design through to shipment. To control its environmental footprint and reconcile this with the company's functional imperatives, our environmental policy provides for the reduction or elimination of hazardous substances. We also focus on compliance with European Union directives and regulations, notably REACH and RoHS.

RoHS COMPLIANCE

SMD CAPACITORS

The capacitor terminations are generally protected by a nickel barrier formed by electrolytic deposit. This barrier gives chip capacitors leaching performance far exceeding the requirements of all applicable standards. The nickel barrier guarantees a minimum resistance to soldering heat for a period of 1 minute at 260°C in a tin-lead (60/40) or tin-lead-silver (62/36/2) bath without noticeable alteration to the solderability. It also allows repeated soldering-unsoldering and the longer soldering times required by reflow techniques.

However nickel barrier amplifies thermal shock and is not recommended for chip sizes equal or greater than CNC Y (30 30) - [C 282 to C 288 - CNC 80 to CNC 94].



LEADED COMPONENTS

As well as for SMD products, leaded capacitors ranges can also be RoHS. These products, which are characterized by the suffix «W» added to the commercial type, are naturally compatible with the soldering alloys used in RoHS mounting technology. The connections coating is generally an alloy SnAg (with a maximum of 4% Ag). However, on a few products that EXXELIA will precise on request, the coating is pure silver.